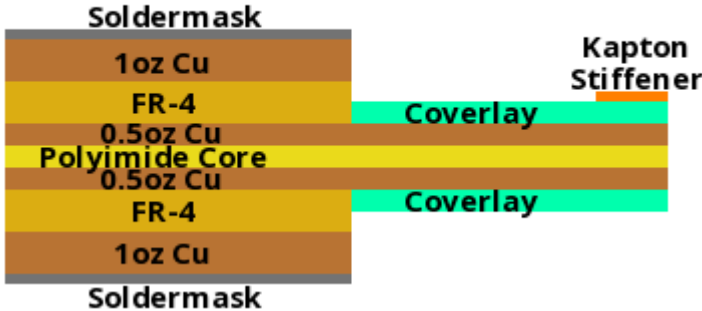


- NOTE: UNLESS OTHERWISE SPECIFIED
1. THIS BOARD SHALL CONFORM TO:
IPC-6013, CURRENT REVISION, CLASS II
IPC-A-600, CURRENT REVISION, CLASS II.
 2. OVERALL RIGID BOARD THICKNESS SHALL BE 1.20mm \pm 10%.
 3. FLEX SECTION SHALL USE A POLYIMIDE CORE SUBSTRATE MATERIAL AND A POLYIMIDE COVERLAY SURFACE.
 4. APPLY KAPTON STIFFENER TO THE DESIGNATED SECTION OF THE FLEX.
 5. APPLY SOLDERMASK OVER RIGID SECTION, COLOR BLACK; MASK SHALL MEET IPC-SM-840.
 6. SEE SUPPLEMENTARY PDF DOCUMENT FOR GENERAL STACKUP GUIDE.
 7. SILKSCREEN SHALL BE WHITE NON-CONDUCTIVE INK, AND IS NOT PERMITTED ON ANY EXPOSED COPPER FEATURES.
 8. SURFACE FINISH SHALL BE IMMERSION GOLD PER IPC 4552. COPPER FEATURES.
 9. MINIMUM ANNULAR RING SHALL BE IN ACCORDANCE WITH IPC-6013 CLASS II.
 10. ALL HOLES SHALL BE LOCATED WITHIN \pm 75 μ m (0.003 INCH) OF TRUE POSITION.
 11. ALL HOLES DIAMETERS INDICATED ARE FINISHED SIZE.
 12. LAYER TO LAYER REGISTRATION SHALL BE \pm 75 μ m (0.003 INCH).
 13. COPPER FEATURES SHALL BE \pm 20% OF SUPPLIED DATA.
 14. COPPER PLATING THICKNESS SHALL BE IN ACCORDANCE WITH IPC-6013 CLASS II.
 15. WARP AND TWIST SHALL BE 0.75% IN ACCORDANCE WITH IPC-TM-650, #2.4.44
 16. REMOVE ALL SHARP EDGES AND BURRS: 75 μ m (0.003 INCH) MAXIMUM.
 17. PCBs SHALL BE PANELIZED. VENDOR TO PROVIDE PANEL DRAWING FOR APPROVAL PRIOR TO STARTING MANUFACTURING.

Stackup Guide



GNU GPLv3+		
Purism SPC		
Sheet:		
File: ext-con-breakout-board.kicad_pcb		
Title: EXT CON Breakout Board		
Size: A4	Date: 2022-07-25	Rev: v0.5
KiCad E.D.A.	kicad 6.0.6-1.fc36	Id: 1/1